










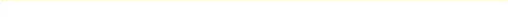



# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.40mil	3.5
4		Top Layer	Copper	1.40mil	
5		Dielectric 1	FR-4	7.00mil	4.2
6		Internal Plane 1	Copper	1.40mil	
7		Dielectric 2	FR-4	50.00mil	4.2
8		Internal Plane 2	Copper	1.40mil	
9		Dielectric 3	FR-4	7.00mil	4.2
10		Bottom Layer	Copper	1.40mil	
11		Bottom Solder	Solder Resist	0.40mil	3.5
12		Bottom Overlay			
13		Bottom Paste			
	Height : 70.40mil				

SiPMBias  
A

B

FlashGate4

C

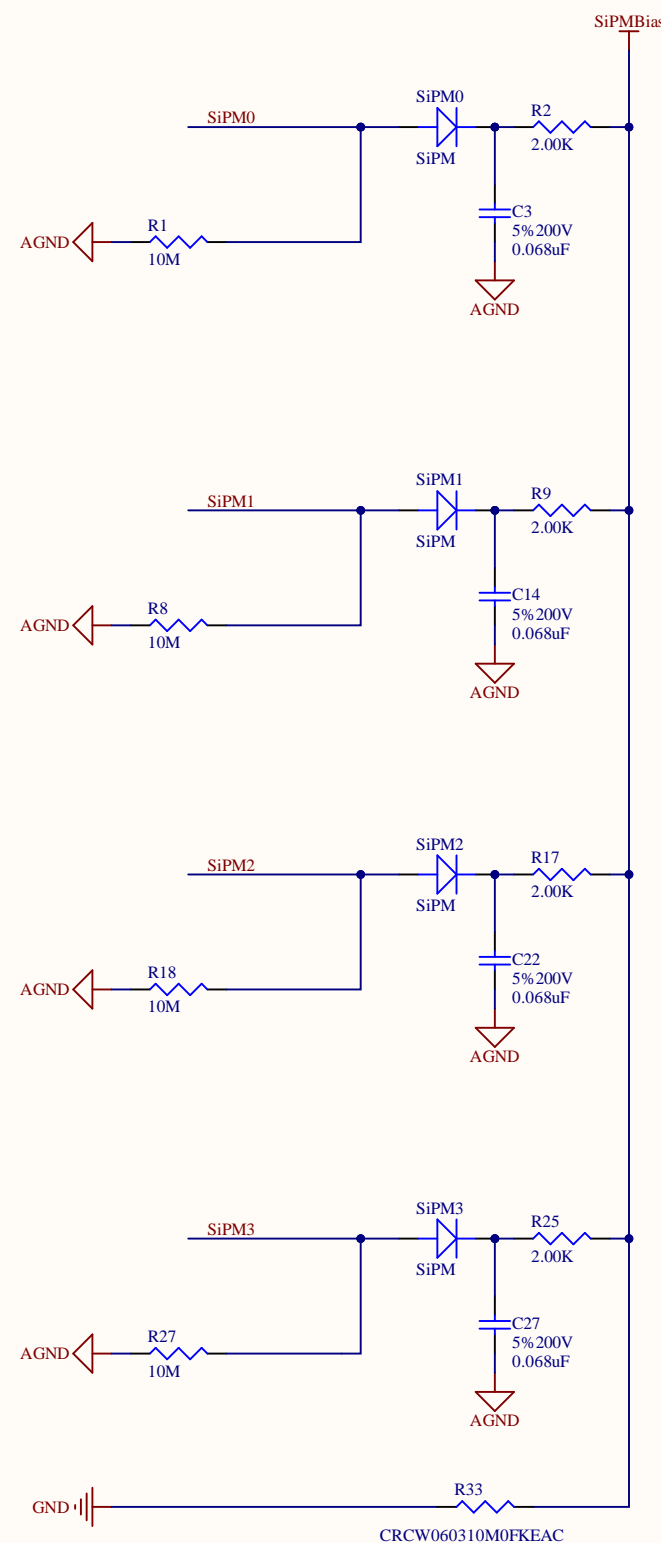
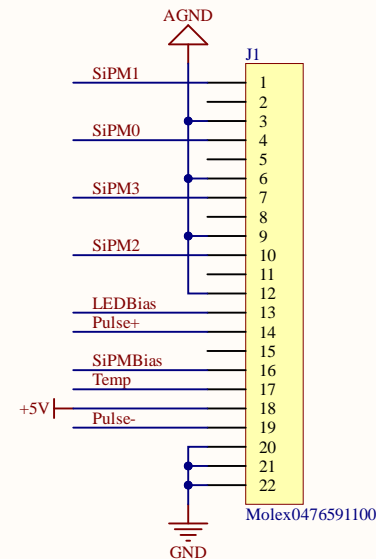
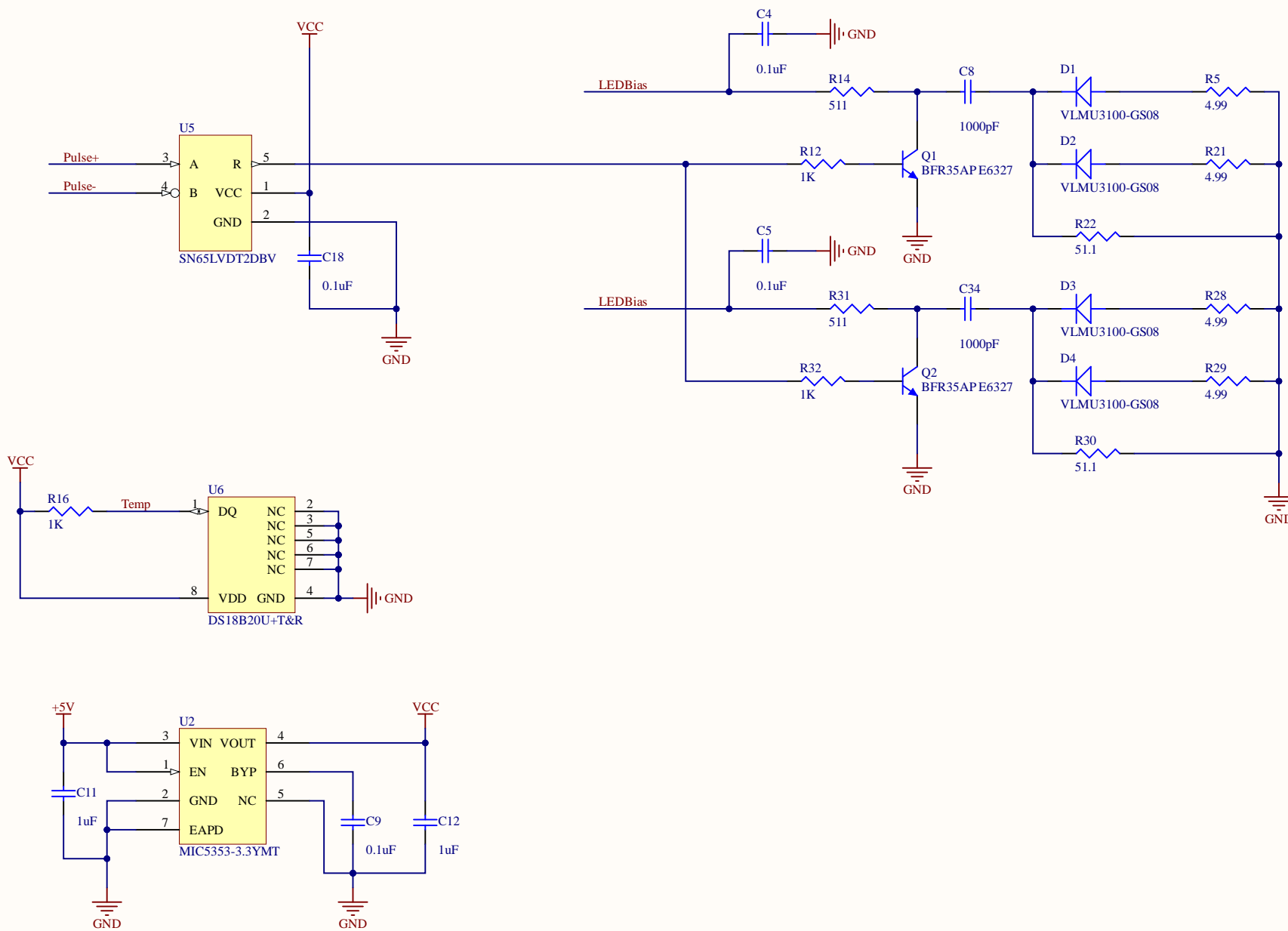
D

A

B

C

D



Title		
LDMX_CMB		
Size	Number	Revision
C		v3.0
Date:	6/16/2022	Sheet bf 1
File:	D:\projects\...\LDMX_CMB_v3.0.SchDoc Drawn By:	